



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Agarwal et al.

**Application No.** 09/590,795

**Filed:** June 8, 2000

**Confirmation No.** 9849

**For:** METHODS FOR FORMING AND  
INTEGRATED CIRCUIT STRUCTURES  
CONTAINING RUTHENIUM AND  
TUNGSTEN CONTAINING LAYERS

**Examiner:** David Vu

**Art Unit:** 2818

**Attorney Reference No.** 6047-53173-01

MAIL STOP AMENDMENT  
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Attorney or Agent  
for Applicant(s)

Date Mailed December 21, 2005

**AMENDMENT AND REPLY TO RESTRICTION REQUIREMENT**

This responds to the Office action dated September 22, 2005. Please amend the referenced application as follows:

**Amendments to the Claims** are reflected in the listing of claims, which begins on page 2.

**Remarks** begin on page 7.